12 Aug	ust 200	y Updated Search		09/868,57
L Number	Hits	Search Text	DB	Time stamp
-	1571	204/\$.ccls. and (wafer or semiconductor) and seal	USPAT;	2004/04/20
			US-PGPUB;	08:59
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	531	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccl		2003/10/27
		204/224r,224m.ccls.) and (wafer or semiconductor)	US-PGPUB;	08:46
		as the tripe timests.) and (water or semiconductor)	EPO; JPO;	00.40
			DERWENT;	
			1	
	218	(/204/108 222 227 242 275 1 207 01 207 07 207 14	IBM_TDB	2002/40/27
-	210	((204/198,232,237,242,275.1,297.01,297.06,297.14.cc		2003/10/27
		204/224r,224m.ccls.) and (wafer or semiconductor))	US-PGPUB;	10:30
		and seal	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	60	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccl		2003/10/27
		204/224r,224m.ccls.) and sponge	US-PGPUB;	09:18
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	2	6176992.pn.	USPAT;	2003/10/27
i		· •	US-PGPUB;	09:25
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	14	("3595089" "4610772" "5024735" "5171412"	USPAT	2003/10/27
		"5429733" "5558568" "5692947" "5755859"	0317(1	09:26
		"5807165" "5833820" "5863412" "5930669"		09.20
ľ		"5933753" "6004880").PN.		
	2	6228233.pn.	LICDAT.	2002 40 407
	٤	υ 220233.μ π.	USPAT;	2003/10/27
			US-PGPUB;	09:33
			EPO; JPO;	
	i		DERWENT;	
			IBW_TDB	
-	2	4807973.pn.	USPAT;	2003/10/27
}			US-PGPUB;	09:33
			EPO; JPO;	
			DERWENT;	
d.	1		IBM_TDB	
-	23	(204/\$.ccls. or 205/\$.ccls.) and datta.in.	USPAT;	2003/10/27
			US-PGPUB;	10:33
			EPO; JPO;	
			DERWENT;	
		}	IBM_TDB	
_	3838	204/198,232,237,242,275.1,297.01,297.06,297.14.ccls		2003/10/27
		204/224r,224m.ccls.	US-PGPUB;	10:53
Ì			EPO; JPO;	10.33
	ļ		DERWENT;	
		,		
L	L		IBM_TDB	

	313	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccl	LISPAT	2003/10/27
-	313	204/196,232,237,242,273.1,297.01,297.00,297.14.00.	US-PGPUB;	10:54
		or cathode or electrode))	EPO; JPO;	10.54
		or carnode or electrode))	DERWENT;	
			IBM_TDB	
_	67	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccl		2003/10/27
	0,	204/224r,224m.ccls.) and (temperature near2 (anode	US-PGPUB;	11:03
		or cathode or electrode))	EPO; JPO;	11.03
		or carnode or electrode))	DERWENT;	
			IBM_TDB	
_	10	3859196.URPN.	USPAT	2003/10/27 11:01
_	30	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccl		2003/10/27 11:13
	50	204/224r,224m.ccls.) and ((temperature near2	US-PGPUB;	2003/10/2/11:13
		control\$5) with (anode or cathode or electrode))	EPO; JPO;	
		commonway with (unode of carnode of electrode))	DERWENT;	
			IBM_TDB	
_	2	("5507923" "6017437").PN.	USPAT	2003/10/27
	_	(3307)23 0017437).114.	001711	11:06
_	25	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccl	LISPAT	2003/10/27 11:19
		204/224r,224m.ccls.) and ((coolant or (cooling adj	US-PGPUB;	2000,10,2,1117
		(fluid or liquid))) with (anode or cathode or	EPO; JPO;	
		electrode))	DERWENT;	
		,	IBM_TDB	
-	531	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccl	_	2003/10/27
		204/224r,224m.ccls.) and (wafer or semiconductor)	US-PGPUB;	11:20
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	375	((204/198,232,237,242,275.1,297.01,297.06,297.14.cc	SUSPAT;	2003/10/27
		204/224r,224m.ccls.) and (wafer or semiconductor))	US-PGPUB;	11:22
		and (coolant or (cooling fluid) or heat or heating)	EPO; JPO;	
			DERWENT;	
			IBW_TDB	
-	176	((204/198,232,237,242,275.1,297.01,297.06,297.14.cc		2003/10/27
		204/224r,224m.ccls.) and (wafer or semiconductor))	US-PGPUB;	11:22
		and ((coolant or (cooling fluid) or heat or heating)	EPO; JPO;	
		with (anode or cahode or electrode))	DERWENT;	
		//204/100 222 227 242 275 4 227 24 227 24 227 14	IBM_TDB	0000 40 407 44 04
-	93	((204/198,232,237,242,275.1,297.01,297.06,297.14.cc		2003/10/27 11:21
		204/224r,224m.ccls.) and (wafer or semiconductor))	US-PGPUB;	
		and ((coolant or (cooling fluid) or heat or heating)	EPO; JPO;	
		near3 (anode or cahode or electrode))	DERWENT;	
_	9	((204/198,232,237,242,275.1,297.01,297.06,297.14.cc	IBM_TDB	2003/10/27 11:21
· -		204/224r,224m.ccls.) and (wafer or semiconductor))	US-PGPUB;	2003/10/2/ 11:21
•		and ((coolant or (cooling adj fluid) or heat or heating)	EPO; JPO;	
		near3 (anode or cahode or electrode))	DERWENT;	
		(IBM_TDB	
_	197	((204/198,232,237,242,275.1,297.01,297.06,297.14.cc		2003/10/27
		204/224r,224m.ccls.) and (wafer or semiconductor))	US-PGPUB;	11:22
;		and (coolant or (cooling adj fluid) or heat or heating)	EPO; JPO;	
		, <u> </u>	DERWENT;	
			IBM_TDB	

	32	(/204/108 222 227 242 275 1 207 01 207 04 207 14	ALICDAT.	0000 40 407
-	32	((204/198,232,237,242,275.1,297.01,297.06,297.14.cc	· ·	2003/10/27
		204/224r,224m.ccls.) and (wafer or semiconductor))	US-PGPUB;	11:22
		and ((coolant or (cooling adj fluid) or heat or heating)	EPO; JPO;	
		with (anode or cahode or electrode))	DERWENT;	
			IBM_TDB	
-	2	("5507923" "6017437").PN.	USPAT	2003/10/27
				11:27
-	0	868577.apn.	USPAT;	2003/10/27
			US-PGPUB;	11:42
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	22	(US-6077412-\$ or US-6017437-\$ or US-5951833-\$	USPAT;	2003/10/27
		or US-5567300-\$ or US-5776330-\$ or	US-PGPUB	11:50
		US-6176992-\$ or US-6228233-\$ or US-6251235-\$	03910108	11.50
		or US-6258240-\$ or US-6261433-\$ or		
		U5-6270647-\$ or US-6328872-\$ or US-6334937-\$		
	,			
		or US-6103096-\$ or US-5284554-\$ or		
		US-3859196-\$ or US-6398926-\$ or US-5228966-\$		
1		or US-5198083-\$ or US-3894925-\$ or		
		US-3637468-\$).did. or (US-20020056647-\$).did.		
-	8	((US-6077412-\$ or US-6017437-\$ or US-5951833-\$	USPAT;	2003/10/27 11:51
		or US-5567300-\$ or US-5776330-\$ or	US-PGPUB;	
		US-6176992-\$ or US-6228233-\$ or US-6251235-\$	EPO; JPO;	
		or US-6258240-\$ or US-6261433-\$ or	DERWENT;	
		US-6270647-\$ or US-6328872-\$ or US-6334937-\$	IBM_TDB]
	1	or US-6103096-\$ or US-5284554-\$ or		1
		US-3859196-\$ or US-6398926-\$ or US-5228966-\$		
	ļ	or US-5198083-\$ or US-3894925-\$ or		
		US-3637468-\$).did. or (US-20020056647-\$).did.)		
		and ((electrolyte or solution or fluid) with		
		(temperature or cool\$4 or heat\$4))		
_	7	((US-6077412-\$ or US-6017437-\$ or US-5951833-\$	USPAT;	2003/10/27
		or US-5567300-\$ or US-5776330-\$ or	US-PGPUB;	12:32
		US-6176992-\$ or US-6228233-\$ or US-6251235-\$	EPO; JPO;	16.36
		or US-6258240-\$ or US-6261433-\$ or	DERWENT;	
]	US-6270647-\$ or US-6328872-\$ or US-6334937-\$		
		or US-6103096-\$ or US-5284554-\$ or	IBW_TDB	
		US-3859196-\$ or US-6398926-\$ or US-5228966-\$		
		•		
		or US-5198083-\$ or US-3894925-\$ or		
		US-3637468-\$).did. or (US-20020056647-\$).did.)		
		and (dc or (direct adj current))		
-	0	868577.apn.	USPAT;	2004/04/20
			US-PGPUB;	08:59
			EPO; JPO;	
			DERWENT;	
			IBW_TDB	
-	2655	204/198,232,237,242,275.1,297.01,297.06,297.14.ccls	USPAT;	2004/04/20
			US-PGPUB;	09:50
1			EPO; JPO;	
			DERWENT;	
			IBM_TDB	

-	68	204/198,232,237,242,275.1,297.01,297.06,297.14.ccls	· LISPAT	2004/04/20
		and (ammeter or (current near (detect\$4 or sensor	US-PGPUB;	10:01
		or sense or sensing or sensed)))	EPO; JPO;	10.01
		or sense or sensing or sensea;;;	DERWENT;	
ĺ			IBM_TDB	
1_	1521	204/224r,224m.ccls.	USPAT;	2004/04/20
	1321	2047 2241 ,224111.0015.		2004/04/20
			US-PGPUB;	10:01
			EPO; JPO;	
			DERWENT;	
	47	204/224n 224m cold and (aminoton an (aminoton an	IBM_TDB	2004/04/20
-	7/	204/224r,224m.ccls. and (ammeter or (current near (detect\$4 or sensor or sense or sensing or sensed)))	USPAT;	2004/04/20
		(detection of sensor of sense of sensing of sensed)))	US-PGPUB;	10:16
			EPO; JPO;	
			DERWENT;	
	42	(204/224m 224m and and (1997)	IBM_TDB	0004/04/00
-	1 46	(204/224r,224m.ccls. and (ammeter or (current near	USPAT;	2004/04/20
	İ	(detect\$4 or sensor or sense or sensing or sensed))))	US-PGPUB;	10:03
		not (204/108 222 227 242 275 4 207 04 207 07 07 44 14	EPO; JPO;	
		(204/198,232,237,242,275.1,297.01,297.06,297.14.ccl	· ·	
		and (ammeter or (current near (detect\$4 or sensor	IBM_TDB	
	1/0/	or sense or sensing or sensed))))		
-	1686	205/118,122,125.ccls.	USPAT;	2004/04/20
			US-PGPUB;	10:04
	1		EPO; JPO;	
			DERWENT;	
	4	205 440 400 405	IBW_LDB	
] -	17	205/118,122,125.ccls. and (ammeter or (current near	USPAT;	2004/04/20
		(detect\$4 or sensor or sense or sensing or sensed)))	US-PGPUB;	10:04
			EPO; JPO;	
			DERWENT;	
		0/0577	IBM_TDB	
-	0	868577.apn.	USPAT;	2004/08/12
			US-PGPUB;	10:49
	ļ		EPO; JPO;	
			DERWENT;	
		204/200	IBW_TDB	
-	614	204/229.8.ccls. 205/775,790.5,791.5.ccls.	USPAT;	2004/08/12
			US-PGPUB;	10:49
			EPO; JPO;	
			DERWENT;	
	_	(204/220 0 1- 205/775 700 5 704 5 1 1 1 1	IBM_TDB	
-	5	(204/229.8.ccls. 205/775,790.5,791.5.ccls.) and	USPAT;	2004/08/12 11:01
		(pinhole or (pin adj hole))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	40	4473705 HDDN	IBM_TDB	
-	18	4473795.URPN.	USPAT	2004/08/12
	,,	(204/220 0 1- 205/275 200 5 201 5 1 1 1 1		10:52
-	64	(204/229.8.ccls. 205/775,790.5,791.5.ccls.) and	USPAT;	2004/08/12
		(cavity or discontinuity)	US-PGPUB;	11:02
			EPO; JPO;	
	1		DERWENT;	
			IBM_TDB	

-	94	(204/229.8.ccls. 205/775,790.5,791.5.ccls.) and	USPAT;	2004/08/12
		(cavity or discontinuity or defect)	US-PGPUB;	11:02
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	12	(204/229.8.ccls. 205/775,790.5,791.5.ccls.) and	USPAT;	2004/08/12
	-	((cavity or discontinuity or defect) with current)	U5-PGPUB;	11:03
			EPO; JPO;	
			DERWENT;	
			IBW_TDB	
-	4	("3373353" "3772520" "3792458"	USPAT	2004/08/12
		"4296372").PN.		11:25
-	10	3792458.URPN.	USPAT	2004/08/12
				11:26